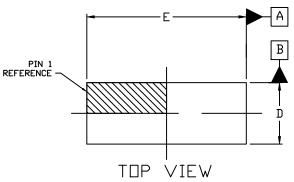


○ 0.03 C

WLCSP40 1.60x4.15x0.33

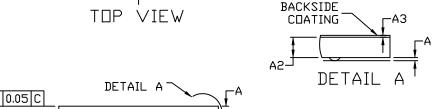
CASE 567XS ISSUE O

DATE 12 APR 2019



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
- 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
- 5. DIMENSION 6 IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

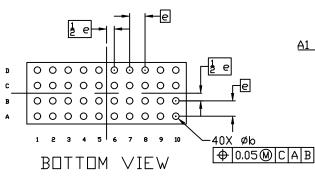


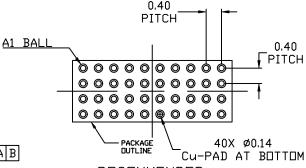
С

SEATING

PLANE

| | MILLIMETERS | | | |
|-----|-------------|--------|--------|--|
| DIM | MIN. | N□M. | MAX. | |
| Α | 0.31 | 0.33 | 0.35 | |
| A1 | 0.034 | 0.040 | 0.046 | |
| A2 | 0.2525 | 0.2650 | 0.2775 | |
| A3 | 0.020 | 0.025 | 0.030 | |
| b | 0.15 | 0.17 | 0.19 | |
| D | 1.575 | 1.600 | 1.625 | |
| E | 4.125 | 4.150 | 4.175 | |
| е | 0.40 BSC | | | |





RECOMMENDED
MOUNTING FOOTPRINT*
NSMD TYPE

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*

SIDE VIEW

° XXXXXXXX AWLYYWW

XXX = Specific Device Code

A = Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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|------------------|------------------------|---|-------------|--|
| DESCRIPTION: | WLCSP40 1.60x4.15x0.33 | | PAGE 1 OF 1 | |

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